

- Extra Small Packaging Style
- Low Jitter
- Low Phase Noise
- Immediate Delivery



Part Numbering Example: CAMs C 3 Q Z - A5 B6 - XXX.XXXX TS

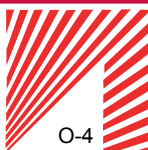
CAMs	C	3	Q	Z	A5	B6	XXX.XXXX	TS
SERIES	OUTPUT	PACKAGE STYLE	VOLTAGE	PACKAGING OPTIONS	OPERATING TEMP.	STABILITY	FREQUENCY	TRI-STATE
CAMs	C=HCMOS	3 = 3.2 X 2.5 Ceramic 5 = 5.0 X 3.2 Ceramic 7 = 5.0 X 7.0 Ceramic	Q = 1.8 V S = 2.5 V L = 3.3 V	Blank = Bulk T = Tube Z = Tape and Reel	Blank = 0°C +70°C A5 = -20°C +70°C A7 = -40°C +85°C	B6 = ±100 ppm BP = ±50 ppm BR = ±25 ppm	1.5~133.000 MHz	TS = Tri-State PD= Power Down NC = No Connect

Specifications:

Description	Min	Typ	Max	Unit
<b>Frequency Range:</b> Programmable to Any Discrete Frequency	1.500		133.000	MHz
<b>Available Stability Options:</b>	-100 -50 -25		100 50 25	ppm ppm ppm
<b>Supply Voltage Options:</b> (1.5–133 MHz)	2.97 2.25 1.62	3.3 2.5 1.8	3.63 2.97 1.98	V
<b>Operating Temperature Range Options:</b>	0 -20 -40		+70 +70 +85	°C °C °C
<b>Storage Temperature:</b>	-55		+125	°C
Aging (PPM/Year) Ta=25C, Vdd=3.3V/2.5V			±5	
<b>Output Level:</b>	HCMOS			
<b>Packaging:</b>	Tape and Reel (1K per Reel) Tube			

Operating Conditions:

Description	Min	Max	Unit
Vdd Rise Time:	100		µS
HCMOS Max Capacitive Load on outputs for CMOS levels Frequency: < 40 MHz Frequency: 40–133 MHz		25 15	pF pF



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**Electrical Characteristics**

Description	TEST CONDITIONS	Min	Typ	Max	Unit
<b>Input Characteristics (Pin 1):</b> V <sub>IL</sub> , Low-Level Input Voltage TO DISABLE OUTPUT				0.2V <sub>dd</sub>	V
V <sub>IH</sub> , High-Level Input Voltage TO ENABLE OUTPUT OR open		0.7V <sub>dd</sub>			
I <sub>IL</sub> , Input Low Current I <sub>IH</sub> , Input High Current	V <sub>IN</sub> = 0V V <sub>IN</sub> = V <sub>dd</sub>			80 10	μA μA
<b>Output Characteristics:</b> V <sub>OL</sub> , Low-Level Output Voltage	8 mA I <sub>OL</sub>			0.4	V
V <sub>OHC</sub> MOS, High-level HCMOS Voltage	-8 mA I <sub>OL</sub>	V <sub>dd</sub> -0.4			V
<b>Power Supply Current: (Loaded)</b>	1.8V V <sub>dd</sub> , OUTPUT FREQ ≤ 133 MHz			15	mA
<b>Tri-State Internal Pull-up:</b>	Output Active when pin 1 high	50	70	90	kΩ
<b>Tri-State Leakage Current:</b>	TS option, Pin 1 low			20	μA
<b>Power Down Current:</b>	PD option, Pin 1 low			10	μA

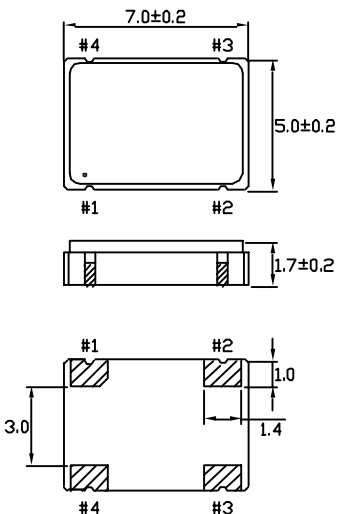
"Tristate internal pull up. Output active when high"

**Output Clock Switching Characteristics**

Description	TEST CONDITIONS	Min	Typ	Max	Unit
<b>Duty Cycle:</b> HCMOS @ V <sub>dd</sub> /2		45		55	%
<b>Output Clock Rise/Fall:</b>	0.2–0.8V <sub>dd</sub> , C <sub>L</sub> = 15		2		nS
<b>Start Up Time:</b>	From power on		3	10	mS
<b>RMS Period Jitter:</b>			7	10	pS
<b>RMS Integrated Jitter:</b>	12kHz to 20MHz		30		pS
<b>Phase Noise:</b>	@ 10kHz			-90	dBc/Hz

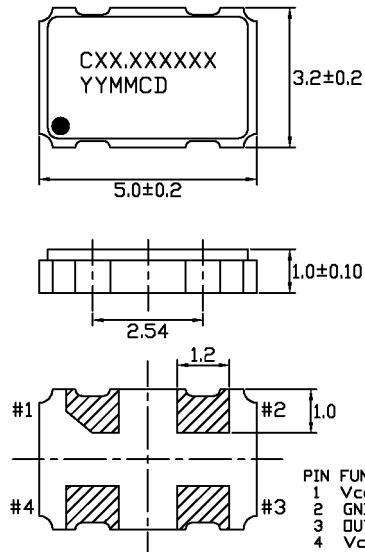


Style 7 5x7 Ceramic SMD



**PIN FUNCTION**  
 1 CONTROL  
 2 GND  
 3 OUTPUT  
 4 Vdd

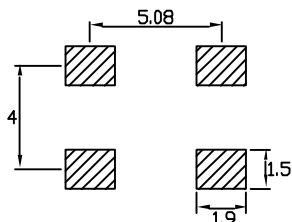
Style 5 5x3.2 Ceramic SMD



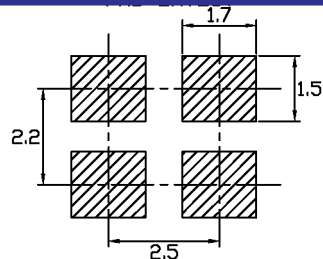
**PIN FUNCTION**  
 1 CONTROL  
 2 GND  
 3 OUTPUT  
 4 Vdd

**PIN FUNCTION**  
 1 Vcont  
 2 GND  
 3 OUT  
 4 Vcc

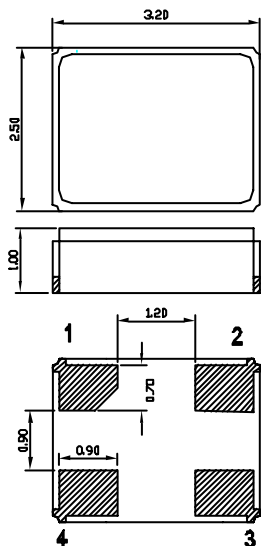
Recommended Solder Pad Layout



Recommended Solder Pad Layout

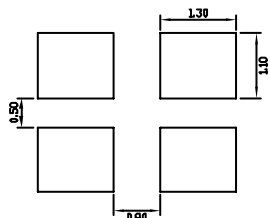


Style 3 3.2x2.5 Ceramic SMD



**PIN FUNCTION**  
 1 CONTROL  
 2 GND  
 3 OUTPUT  
 4 Vdd

Recommended Solder Pad Layout



*Note: Bypass Vdd to GND with a 0.01µF capacitor*